



Product/Process Change Notice - PCN 14_0254 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: Bump and Assembly Transfer of Select 10x10 and 12x12 Flip Chip Products

Publication Date: 25-Nov-2014

Effectivity Date: 31-Mar-2015 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI is transferring the bumping and assembly process for select 10x10, and 12x12 flip chip products.

The bumping process will be transferring from TSMC to Amkor Taiwan. The material change is as follows:

- The bump composition will change from 63Sn37Pb to 98.2Sn1.8Ag.

The assembly process will be transferring from the current STATS ChipPAC factory (SCK1) in Korea to a new factory location in Korea (SCK3). The material changes are as follows:

- The under fill material will change from Shinetsu 75LV or Namics U8439-1 to Namics U8410-73C.
- Change the Solder On Pad Composition from 63Sn37Pb to SAC305.
- Add Solder On Pad (SAC305) for select products.
- Change Solder mask material from AUS303 to AUS410 for select products.

Refer to the material change summary attachment for change details of the affected products.

Reason For Change

TSMC will be obsoleting the bumping process on 200 mm wafers by the end of 2015.

STATS ChipPAC factory (SCK1) in Korea will close by May 2015.

The material changes are for Pb-free compatibility.

Impact of the change (positive or negative) on fit, form, function & reliability

The transfer will have no impact on the form, fit, function and reliability of the devices.

Summary of Supporting Information

Qualification will be performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Detailed Change Description

ADI_PCN_14_0254_Rev_-_Material Change Summary.pptx

Attachment 2: Type: Qualification Plan

ADI_PCN_14_0254_Rev_-_Qualification Plan Summary.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models**Added Parts On This Revision - Product Family / Model Number (33)**

AD9119 / AD9119BBCZ	AD9119 / AD9119BBCZRL	AD9129 / AD9129BBC	AD9129 / AD9129BBCRL	AD9129 / AD9129BBCZ
AD9129 / AD9129BBCZRL	AD9148 / AD9148BBCZ	AD9148 / AD9148BBCZRL	AD9148 / AD9148BBPZ	AD9148 / AD9148BBPZRL
AD9652 / AD9652BBCZ-310	AD9652 / AD9652BBCZRL7-310	AD9734 / AD9734BBCZ	AD9734 / AD9734BBCZRL	AD9735 / AD9735BBCZ
AD9735 / AD9735BBCZRL	AD9736 / AD9736BBC	AD9736 / AD9736BBCRL	AD9736 / AD9736BBCZ	AD9736 / AD9736BBCZRL
AD9737A / AD9737ABBCZ	AD9737A / AD9737ABBCZRL	AD9739 / AD9739BBC	AD9739 / AD9739BBCRL	AD9739 / AD9739BBCZ
AD9739 / AD9739BBCZRL	AD9739A / AD9739ABBCZ	AD9739A / AD9739ABBCZRL	AD9789 / AD80258BBCZ	AD9789 / AD9789BBC
AD9789 / AD9789BBCRL	AD9789 / AD9789BBCZ	AD9789 / AD9789BBCZRL		

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	25-Nov-2014	31-Mar-2015	Initial Release

Analog Devices, Inc.

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